

April 28, 2008

DMI International introduces HC300 (TM), a new, cost-effective solder wave palleting / fixture material.

DMI International is the largest distributor of HC300 composite material. Manufactured in USA, the HC300 material offers excellent benefits in overall performance while helping to defray increasing budgetary constraints for necessary palleting / fixtures in PCB (Printed Circuit Board) production line processing. As an illustrative point, for the past year and a half DMI has been using the HC300 material for a large base of both new and repeat customer palleting needs. Translated, HC300 comprise 2000 plus solder wave pallets / fixtures that are currently in production line usage to date, each without a single issue regarding the material's performance integrity.

HC300 is constructed from a proprietary polyester resin with a reinforcement of isotropic glass filament. Slight compliancy from polyester increases toughness, an integral property variance that allows thin wall cross-sections without fracture. This compliancy also causes the material to be less rigid than 100% epoxy composites, but the compliancy is more than sufficient for most applications. In addition, polyester resin compliancy saves 35% on costs associated with mill bit replacement as compared to the epoxy resin materials. Equally as important, there is less filament residue irritation for finished product handling purposes.



HC300 is capable of 6k-12k passes through the wave solder process; material longevity is dependent on cleaning and allowing the tooling to cool between cycles. Additionally, industry feedback indicates HC300 is less reactive to fluxes that cause premature breakdown in other palleting / fixture materials. In practice, and over thousands of cycles, HC300 demonstrates excellent dimensional stability.

"The HC300 composite has enabled DMI International to compete with the lower labor rates of Mexico," said DMI International's President, Raj Savara. "Over the last year, the other large material manufacturers in the market have had to raise prices - in large part due to the exchange rate issues. For DMI's custom wave solder palleting side of the business, the introduction of HC300 has allowed us to maintain lower prices to our customers without sacrificing the same superior performance expected and required for each of their specific manufacturing needs. Our customer's confidence in the material's property integrity and their repeated request for palleting and assembly aids made from the HC300 material has prompted us to include the resale of HC300 as part of our company's product offering."

DMI International has been manufacturing solder wave pallets and electronic assembly fixtures for 20 years. Over the last year, DMI has maintained a 99% on-time delivery of all customer products. Offering superior customer service, DMI International's capabilities center on customized product performance by offering a wide range of engineering design and manufacturing process services for customers in the electronic assembly industry. Please contact DMI International for your production line needs or for material sales at www.dmipallet.com or 800 886-1468. DMI will be exhibiting at NEPCON East 2008 on April 30-May 1, booth number 847.